



PMEG2015EJ

20 V, 1.5 A very low V_F MEGA Schottky barrier rectifier in SOD323F package

Rev. 01 — 2 March 2005

Product data sheet

1. Product profile

1.1 General description

Planar Maximum Efficiency General Application (MEGA) Schottky barrier rectifier with an integrated guard ring for stress protection encapsulated in a SOD323F (SC-90) very small and flat SMD plastic package.

1.2 Features

- Forward current: 1.5 A
- Very low forward voltage
- Very small and flat SMD package

1.3 Applications

- Low voltage rectification
- High efficiency DC-to-DC conversion
- Voltage clamping
- Inverse polarity protection
- Low and medium power general applications

1.4 Quick reference data



Table 1: Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
I_F	forward current	$T_{sp} \leq 55\text{ °C}$	-	-	1.5	A
V_R	reverse voltage		-	-	20	V
V_F	forward voltage	$I_F = 1500\text{ mA}$	[1] -	560	660	mV

[1] Pulse test: $t_p \leq 300\text{ }\mu\text{s}$; $\delta \leq 0.02$.

2. Pinning information

Table 2: Pinning

Pin	Description	Simplified outline	Symbol
1	cathode		 <i>sym001</i>
2	anode		

3. Ordering information

Table 3: Ordering information

Type number	Package		
	Name	Description	Version
PMEG2015EJ	SC-90	plastic surface mounted package; 2 leads	SOD323F

4. Marking

Table 4: Marking codes

Type number	Marking code
PMEG2015EJ	EL

5. Limiting values

Table 5: Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V_R	reverse voltage		-	20	V
I_F	forward current	$T_{sp} \leq 55\text{ °C}$	-	1.5	A
I_{FRM}	repetitive peak forward current	$t_p \leq 1\text{ ms}$; $\delta \leq 0.25$	-	5.5	A
I_{FSM}	non-repetitive peak forward current	$t = 8\text{ ms square wave}$	[1] -	10	A
P_{tot}	total power dissipation	$T_{amb} \leq 25\text{ °C}$	[1] -	0.36	mW
			[2] -	0.83	mW
T_j	junction temperature		-	150	°C
T_{amb}	ambient temperature		-65	+150	°C
T_{stg}	storage temperature		-65	+150	°C

[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.

[2] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm².

6. Thermal characteristics

Table 6: Thermal characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit	
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	[1][2]	-	-	350	K/W
			[1][3]	-	-	150	K/W
$R_{th(j-sp)}$	thermal resistance from junction to solder point		-	-	55	K/W	

- [1] For Schottky barrier diodes thermal run-away has to be considered, as in some applications the reverse power losses P_R are a significant part of the total power losses. Nomograms for determining the reverse power losses P_R and $I_{F(AV)}$ rating will be available on request.
- [2] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.
- [3] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm².

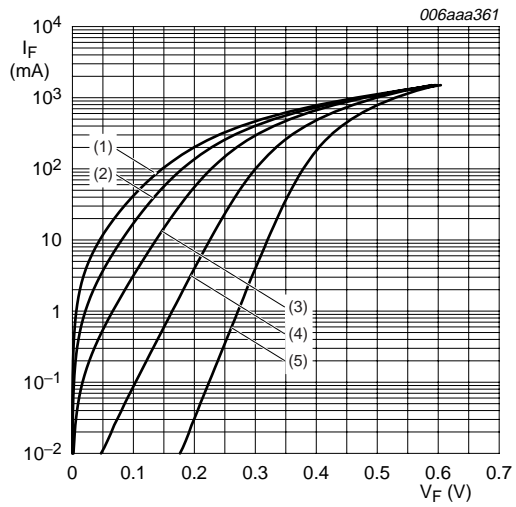
7. Characteristics

Table 7: Characteristics

$T_{amb} = 25^\circ\text{C}$ unless otherwise specified.

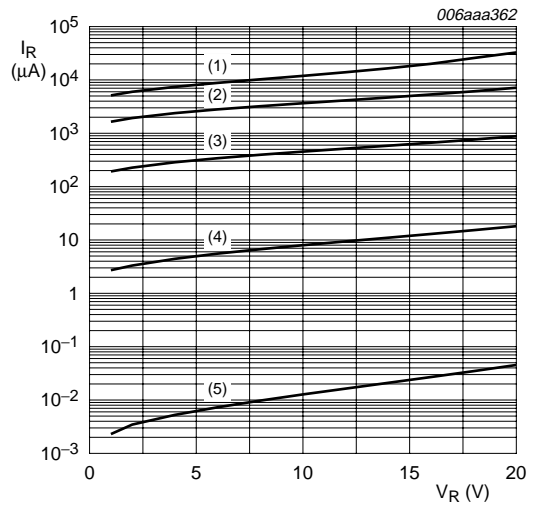
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_F	forward voltage	see Figure 1 ;	[1]			
		$I_F = 10\text{ mA}$	-	240	270	mV
		$I_F = 100\text{ mA}$	-	300	350	mV
		$I_F = 500\text{ mA}$	-	400	460	mV
		$I_F = 1000\text{ mA}$	-	480	550	mV
		$I_F = 1500\text{ mA}$	-	560	660	mV
I_R	reverse current	see Figure 2 ;				
		$V_R = 5\text{ V}$	-	5	10	μA
		$V_R = 8\text{ V}$	-	7	20	μA
		$V_R = 10\text{ V}$	-	8	30	μA
		$V_R = 15\text{ V}$	-	10	50	μA
		$V_R = 20\text{ V}$	-	15	70	μA
C_d	diode capacitance	$V_R = 1\text{ V}$; $f = 1\text{ MHz}$; see Figure 3	-	40	50	pF

- [1] Pulse test: $t_p \leq 300\ \mu\text{s}$; $\delta \leq 0.02$.



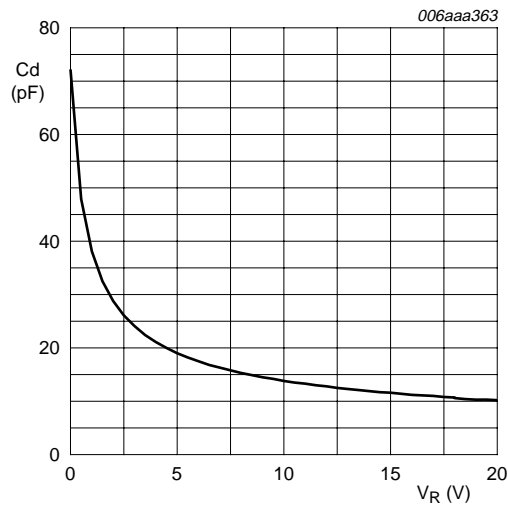
- (1) $T_{amb} = 150\text{ }^{\circ}\text{C}$
- (2) $T_{amb} = 125\text{ }^{\circ}\text{C}$
- (3) $T_{amb} = 85\text{ }^{\circ}\text{C}$
- (4) $T_{amb} = 25\text{ }^{\circ}\text{C}$
- (5) $T_{amb} = -40\text{ }^{\circ}\text{C}$

Fig 1. Forward current as a function of forward voltage; typical values



- (1) $T_{amb} = 150\text{ }^{\circ}\text{C}$
- (2) $T_{amb} = 125\text{ }^{\circ}\text{C}$
- (3) $T_{amb} = 85\text{ }^{\circ}\text{C}$
- (4) $T_{amb} = 25\text{ }^{\circ}\text{C}$
- (5) $T_{amb} = -40\text{ }^{\circ}\text{C}$

Fig 2. Reverse current as a function of reverse voltage; typical values



$T_{amb} = 25\text{ }^{\circ}\text{C}; f = 1\text{ MHz}$

Fig 3. Diode capacitance as a function of reverse voltage; typical values

8. Package outline

Plastic surface mounted package; 2 leads

SOD323F

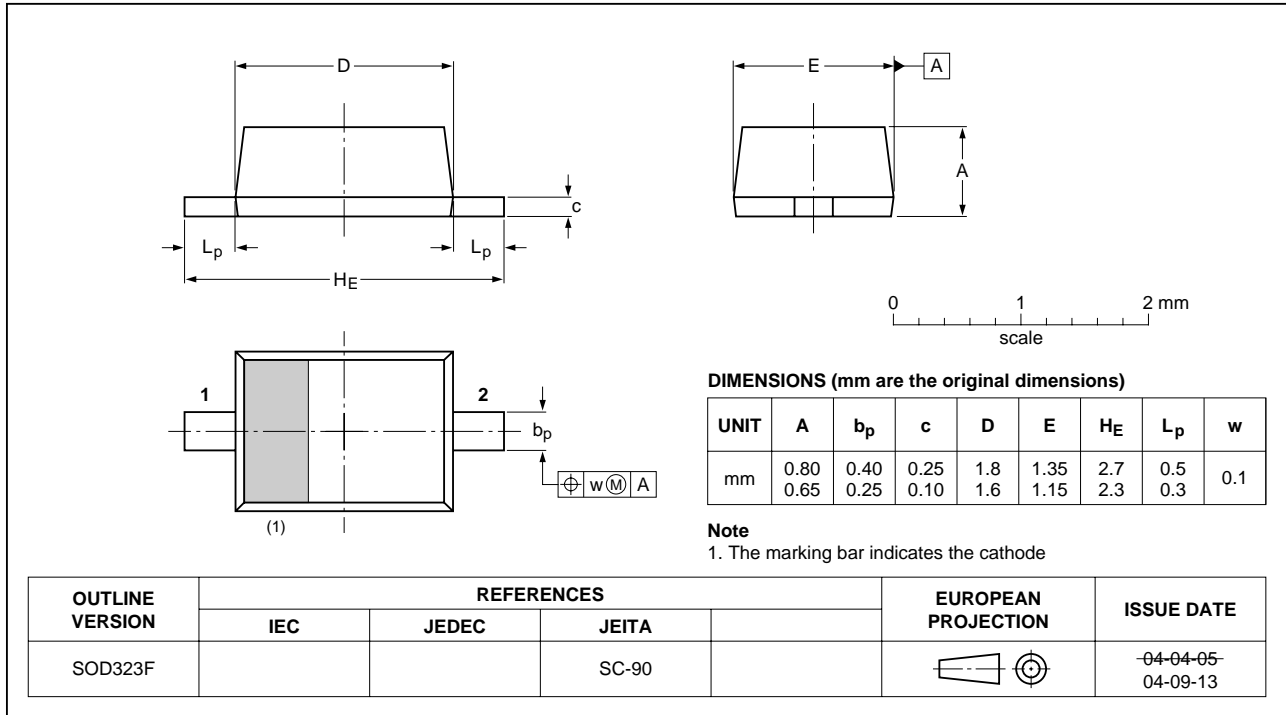


Fig 4. Package outline SOD323F (SC-90)

9. Packing information

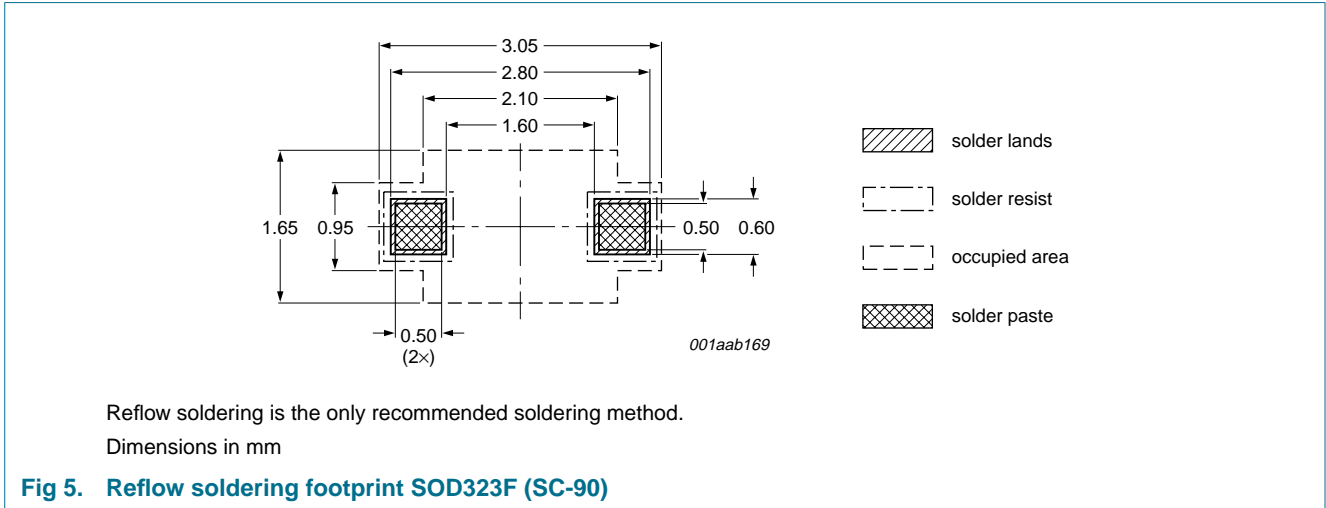
Table 8: Packing methods

The -xxx numbers are the last three digits of the 12NC ordering code. [\[1\]](#)

Type number	Package	Description	Packing quantity	
			3000	10000
PMEG2015EJ	SOD323F	4 mm pitch, 8 mm tape and reel	-115	-135

[1] For further information and the availability of packing methods, see [Section 15](#).

10. Soldering



11. Revision history

Table 9: Revision history

Document ID	Release date	Data sheet status	Change notice	Doc. number	Supersedes
PMEG2015EJ_1	20050302	Product data sheet	-	9397 750 14594	-

12. Data sheet status

Level	Data sheet status ^[1]	Product status ^{[2] [3]}	Definition
I	Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
II	Preliminary data	Qualification	This data sheet contains data from the preliminary specification. Supplementary data will be published at a later date. Philips Semiconductors reserves the right to change the specification without notice, in order to improve the design and supply the best possible product.
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[1] Please consult the most recently issued data sheet before initiating or completing a design.

[2] The product status of the device(s) described in this data sheet may have changed since this data sheet was published. The latest information is available on the Internet at URL <http://www.semiconductors.philips.com>.

[3] For data sheets describing multiple type numbers, the highest-level product status determines the data sheet status.

13. Definitions

Short-form specification — The data in a short-form specification is extracted from a full data sheet with the same type number and title. For detailed information see the relevant data sheet or data handbook.

Limiting values definition — Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 60134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

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Date of release: 2 March 2005
Document number: 9397 750 14594

Published in The Netherlands